



DATE: 10th October, 2016

PCN #: 2208

PCN Title: Qualification of New Lead Frame and Mold Compound and Conversion to Copper Bond Wire on Selected Zener Products.

Dear Customer:

This is an announcement of change(s) to products that are currently being offered by Diodes Incorporated.

We request that you acknowledge receipt of this notification within 30 days of the date of this PCN. If you require samples for evaluation purposes, please make a request within 30 days as well. Otherwise, samples may not be built prior to this change. Please refer to the implementation date of this change as it is stated in the attached PCN form. Please contact your local Diodes sales representative to acknowledge receipt of this PCN and for any sample requests.

The changes announced in this PCN will not be implemented earlier than 90 days from the notification date stated in the attached PCN form.

Previously agreed upon customer specific change process requirements or device specific requirements will be addressed separately.

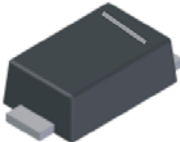
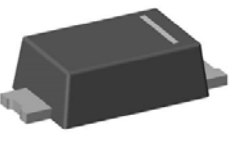
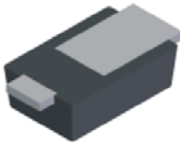
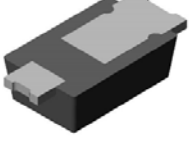
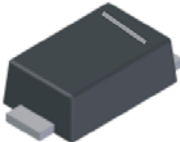
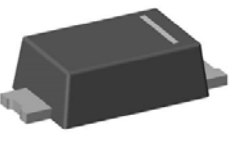
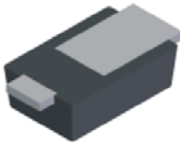
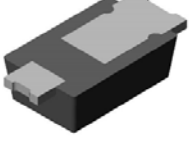
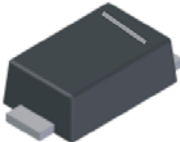
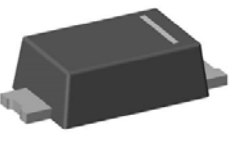
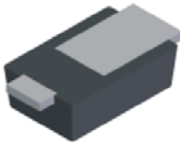
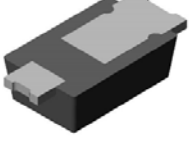
For questions or clarification regarding this PCN, please contact your local Diodes sales representative.

Sincerely,

Diodes Incorporated PCN Team

PRODUCT CHANGE NOTICE

PCN-2208 REV 00

Notification Date:	Implementation Date:	Product Family:	Change Type:	PCN #:						
10 th October, 2016	9 th January, 2017	Discrete Products	Assembly Materials	2208						
TITLE										
Qualification of New Lead Frame and Mold Compound and Conversion to Copper Bond Wire on Selected Zener Products										
DESCRIPTION OF CHANGE										
<p>This PCN is being issued to notify customers that in order to improve product manufacturability, Diodes Incorporated has qualified a new lead frame (with corresponding change in contact layout as pictured below) and mold compound as well as Copper bond wire for Zener diode products listed below. The package type will be changed from POWERDI-323 (Current) to POWERDI-323B (Future) due to the lead frame change.</p> <p>There is no change to Package Outline Dimensions and Suggested Pad Layout specified in the device data sheet.</p>										
<table border="1"> <thead> <tr> <th>Current POWERDI-323 Package</th> <th>Future POWERDI-323B Package</th> </tr> </thead> <tbody> <tr> <td></td> <td></td> </tr> <tr> <td></td> <td></td> </tr> </tbody> </table>					Current POWERDI-323 Package	Future POWERDI-323B Package				
Current POWERDI-323 Package	Future POWERDI-323B Package									
										
										
<p>Full electrical characterization and reliability testing has been completed on representative part numbers built with new lead frame, mold compound and Cu wire to ensure there is no change to product reliability, device functionality or electrical specifications in the device datasheet.</p> <p>There will be no change to the Fit or Function of affected products.</p>										
IMPACT										
No change in datasheet parameters										
PRODUCTS AFFECTED										
PD3Z284C10-7	PD3Z284C16-7	PD3Z284C27-7	PD3Z284C3V0-7	PD3Z284C4V7-7	PD3Z284C6V8-7					
PD3Z284C11-7	PD3Z284C18-7	PD3Z284C2V4-7	PD3Z284C3V3-7	PD3Z284C5V1-7	PD3Z284C7V5-7					
PD3Z284C12-7	PD3Z284C20-7	PD3Z284C2V7-7	PD3Z284C3V6-7	PD3Z284C5V6-7	PD3Z284C9V1-7					
PD3Z284C15-7	PD3Z284C24-7	PD3Z284C39-7	PD3Z284C4V3-7	PD3Z284C6V2-7						



WEB LINKS	
Manufacturer's Notice:	http://www.diodes.com/quality/pcns
For More Information Contact:	http://www.diodes.com/contacts
Data Sheet:	http://www.diodes.com/products
DISCLAIMER	
Unless a Diodes Incorporated Sales representative is contacted in writing within 30 days of the posting of this notice, all changes described in this announcement are considered approved.	